Combinational Chips

Project Submission : 100 points

Due Date: Submit on eCampus by Monday, July 13th, 11:59 PM

Grading

(A) Project Submission [100%]: Demo logistics will be posted on Slack on #Project1 channel

You will be graded for correctness of the chips (hdl) you have designed and coded. TA's will run tests on all the HDL codes downloaded from your eCampus using Nand2tetris software (Hardware Simulator). So, make sure to test and verify your codes before finally submitting on eCampus.

Rubric: Each chip needs to pass all its test cases to get full credit, else you will receive a **0 point** on that chip.

Deliverables & Submission

You need to turn in **the completed HDL files for all the chips** implemented. In addition, you need to turn in the completed **tst and cmp files** for the **three advanced chips (negation, barrel shifter, and combo add/sub).** Put your **full name** in the introductory comment present in each HDL code. Use relevant code comments and indentation. Also, include the **cover sheet** with your signature. Zip all the required files and the signed cover sheet into a compressed file *FirstName-LastName-UIN.zip* . **Submit this zip file on eCampus.**

Late Submission Policy: Refer to the Syllabus

Full Name: **Section:**   **UIN:**

Any assignment turned in without a fully completed cover page will NOT BE GRADED.

Please list all below all sources (people, books, web pages, etc) consulted regarding this assignment:

CSCE 312 Students	Other People	Printed Material	Web Material (URL)	Other
1.	1.	1.	1.	1.
2.	2.	2.	2.	2.
3.	3.	3.	3.	3.

Please consult the Aggie Honor System Office for additional information regarding academic misconduct – it is your responsibility to understand what constitutes academic misconduct and to ensure that you do not commit it.

I certify that I have listed above all the sources that I consulted regarding this assignment, and that I have not received nor given any assistance that is contrary to the letter or the spirit of the collaboration guidelines for this assignment.

eCampus Submission Date: _____

Printed Name (in lieu of a signature): _____